

N and P-Channel Enhancement Mode Power MOSFET

Description

The NCE4606B uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

N-Channel

 V_{DS} = 30V, I_{D} =6A

 $R_{DS(ON)}$ < 25m Ω @ V_{GS} =10V

 $R_{DS(ON)}$ < 44m Ω @ V_{GS} =4.5V

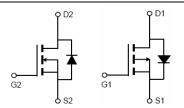
P-Channel

 $V_{DS} = -30V, I_{D} = -6A$

 $R_{DS(ON)}$ < 39m Ω @ V_{GS} =-10V

 $R_{DS(ON)}$ < 51m Ω @ V_{GS} =-4.5V

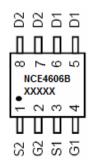
- High power and current handing capability
- Lead free product is acquired
- Surface mount package



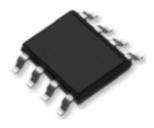
N-channel

P-channel

Schematic diagram



Marking and pin assignment



SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE4606B	NCE4606B	SOP-8	Ø330mm	12mm	4000 units

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Paramet	Symbol	N-Channel	P-Channel	Unit		
Drain-Source Voltage		V _{DS}	30	-30	V	
Gate-Source Voltage		V _{GS}	±20	±20	V	
Continuous Dusin Comment	T _A =25℃	1	6		^	
Continuous Drain Current	T _A =70℃	- I _D	5.0	-5.0	Α	
Pulsed Drain Current (Note 1)		I _{DM}	24	-24	Α	
Maximum Power Dissipation T _A =25℃		P _D	2.0	2.0	W	
Operating Junction and Storage Te	T_{J} , T_{STG}	-55 To 150	-55 To 150	$^{\circ}$		

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	N-Ch	62.5	°C/W
Thermal Resistance, Junction-to-Ambient (Note2)	R _{0JA}	P-Ch	62.5	°C/W



N-CH Electrical Characteristics ($T_A=25$ $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA		33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)				•		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1	1.6	3	V
Drain Course On Chata Basistanas	Б	V _{GS} =10V, I _D =6A	-	20.5	25	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V_{GS} =4.5V, I_D =6A	-	31	44	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =6A	15	-	-	S
Dynamic Characteristics (Note4)			•	•		
Input Capacitance	C _{lss}	\/ 45\/\/ 0\/	-	575	-	PF
Output Capacitance	C _{oss}	V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	75	-	PF
Reverse Transfer Capacitance	C _{rss}	r=1.0lvlm2	-	66.5	-	PF
Switching Characteristics (Note 4)				•		
Turn-on Delay Time	t _{d(on)}		-	4.5	-	nS
Turn-on Rise Time	t _r	V_{DD} =15V, R_L =2.5 Ω	-	2.5	-	nS
Turn-Off Delay Time	$t_{\sf d(off)}$	V_{GS} =10 V , R_{GEN} =3 Ω	-	14.5	-	nS
Turn-Off Fall Time	t _f		-	3.5	-	nS
Total Gate Charge	Qg	\/ -45\/ -64	-	14.8	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =6A,	-	2.6	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	2.9	-	nC
Drain-Source Diode Characteristics			•	•		
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =6A	-	0.8	1.2	V



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P-CH Electrical Characteristics (T_A=25 [°]C unless otherwise noted)

Parameter	Parameter Symbol		Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	<u> </u>			•		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-1.3	-1.65	-2.5	V
Duain Course On Otata Basistana	Б	V _{GS} =-10V, I _D =-6A	-	32	39	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-6A	-	38.5	51	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-6A	10	-	-	S
Dynamic Characteristics (Note4)	<u> </u>			•		
Input Capacitance	C _{Iss}	\/ 45\/\/ 0\/	-	575	-	PF
Output Capacitance	C _{oss}	V_{DS} =-15V, V_{GS} =0V, F=1.0MHz	-	75	-	PF
Reverse Transfer Capacitance	C _{rss}	r-1.0ivinz	-	66	-	PF
Switching Characteristics (Note 4)	<u> </u>			•		
Turn-on Delay Time	t _{d(on)}		-	7.5	-	nS
Turn-on Rise Time	t _r	V_{DD} =-15V, R_L =2.5 Ω	-	5.5	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10 V , R_{GEN} =6 Ω	-	19	-	nS
Turn-Off Fall Time	t _f		-	7	-	nS
Total Gate Charge	Qg	\/ - 45\/	-	11.1	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =-15V, I_{D} =-6A	-	2.0	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =-10V	-	2.6	-	nC
Drain-Source Diode Characteristics			•	•	•	
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-6A	-	-	-1.2	V

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5 The spike duty cycle 5% max, limited by junction temperature $T_J(MAX)$ =125 $^\circ$ C



N- Channel Typical Electrical and Thermal Characteristics (Curves)

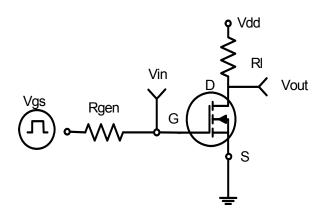
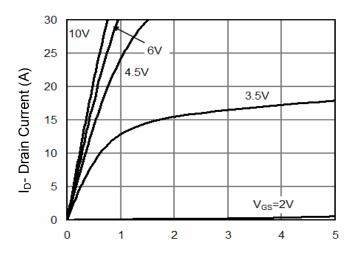


Figure 1:Switching Test Circuit



Vds Drain-Source Voltage (V)
Figure 3 Output Characteristics

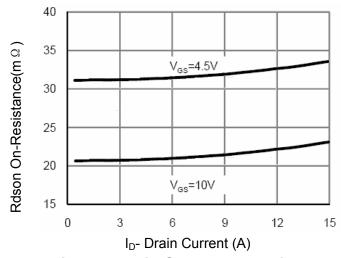


Figure 5 Drain-Source On-Resistance

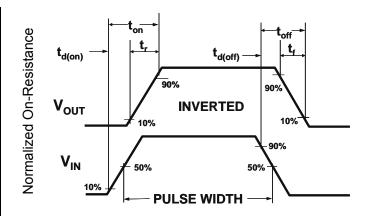


Figure 2:Switching Waveforms

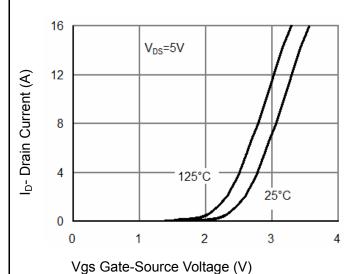


Figure 4 Transfer Characteristics

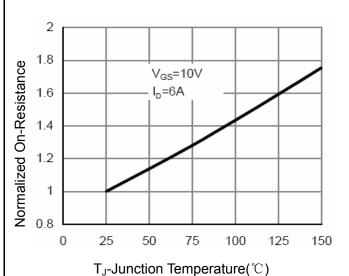


Figure 6 Drain-Source On-Resistance



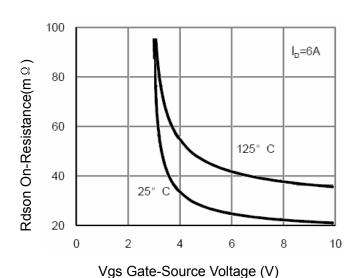
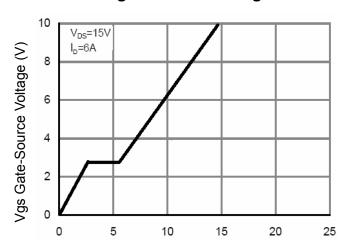


Figure7 Rdson vs Vgs



Qg Gate Charge (nC) Figure 9 Gate Charge

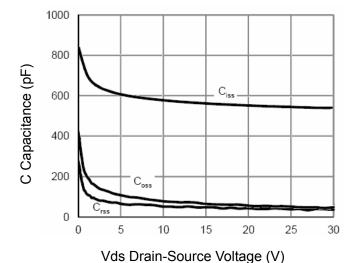
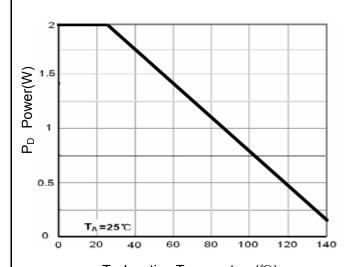


Figure 11 Capacitance vs Vds



 T_J -Junction Temperature($^{\circ}$ C) Figure 8 Power Dissipation

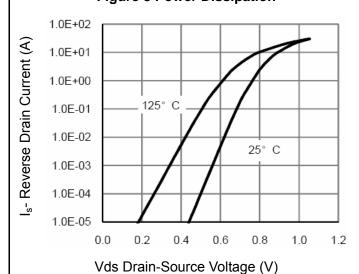
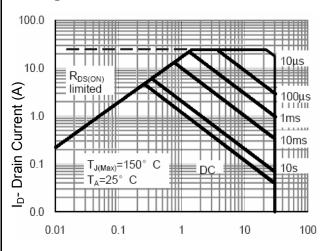


Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)
Figure 12 Safe Operation Area



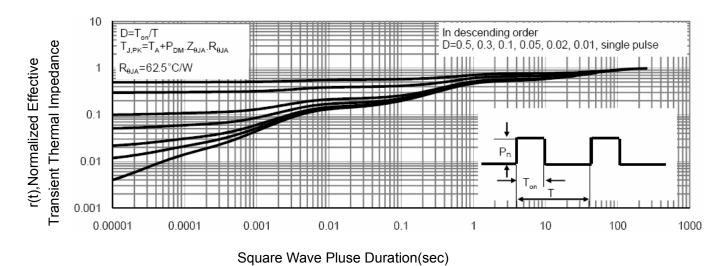
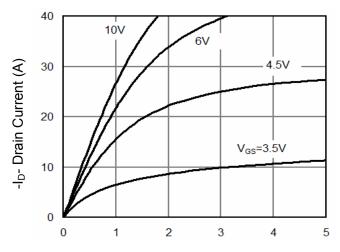


Figure 13 Normalized Maximum Transient Thermal Impedance

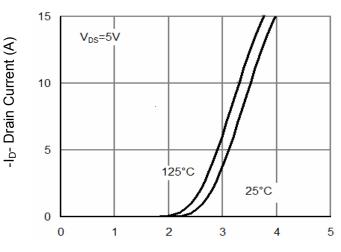


P- Channel Typical Electrical and Thermal Characteristics (Curves)



-Vds Drain-Source Voltage (V)





-Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

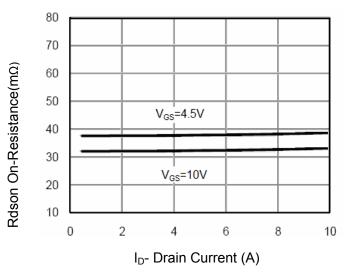


Figure 3 Rdson- Drain Current

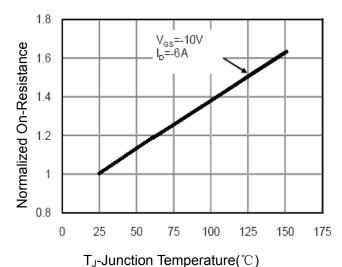


Figure 4 Rdson-Junction Temperature

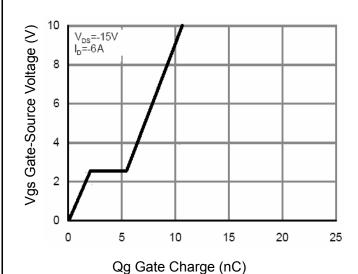


Figure 5 Gate Charge

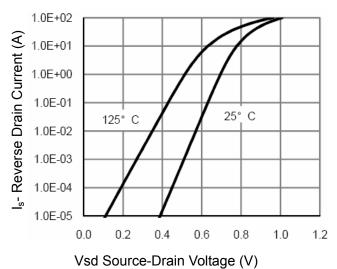


Figure 6 Source- Drain Diode Forward



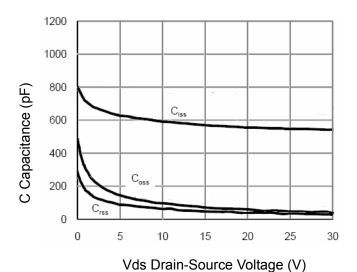
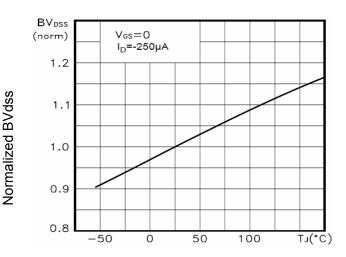
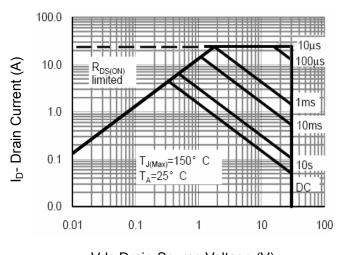


Figure 7 Capacitance vs Vds



 T_J -Junction Temperature (°C) Figure 9 BV_{DSS} vs Junction Temperature



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area

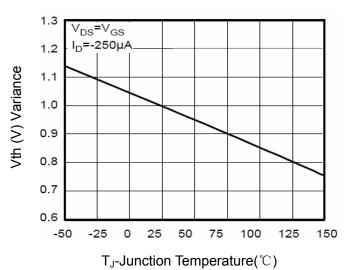


Figure 10 V_{GS(th)} vs Junction Temperature

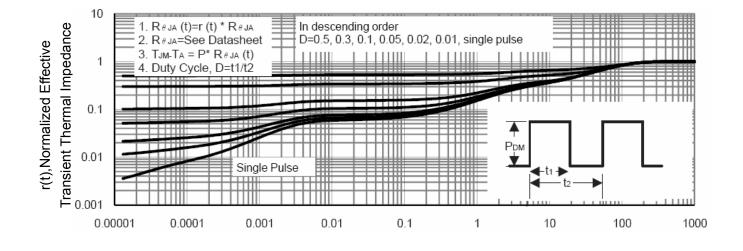
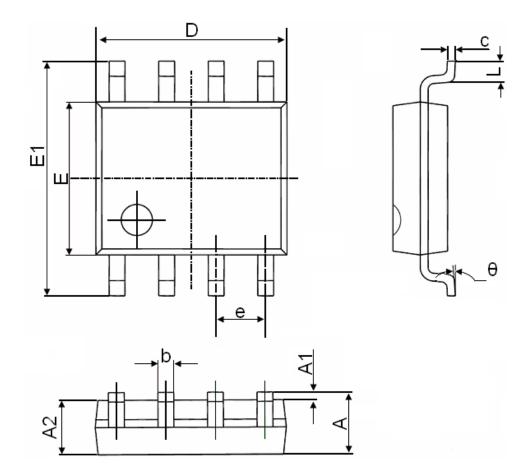


Figure 11 Normalized Maximum Transient Thermal Impedance

Square Wave Pluse Duration(sec)



SOP-8 Package Information



Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
Е	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	1.270(BSC)		(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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